Special Issue

Micro and Nano Abrasive Machining

Message from the Guest Editor

The application of micro and nano scale manufacturing was established during the development of the transistor in the late 1940s. In this Special Issue addressing micro and nano abrasive processing, the publishers invite you to submit research papers, review, case studies, and technical notes on the rapid development of manufacturing processes at the micro and nanoscale that are focused on machining and grinding operations. Authors are invited to contribute experimental, computational, theoretical, and practical applications of machining and grinding at the micro and nanoscales. Keywords:

- micro abrasives
- nano abrasives
- micro grinding
- nano grinding
- abrasives
- nanotechnology
- microtechnology
- processing
- manufacturing

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Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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